

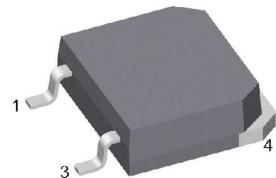
High Voltage Thyristor

V_{RRM} = 2200 V
 I_{TAV} = 60 A
 V_T = 2,62 V

Single Thyristor

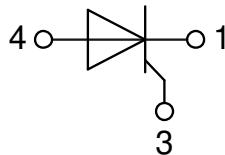
Part number

CNE60E2200TZ



Backside: anode

 E72873



Features / Advantages:

- Thyristor for line and moderate frequencies
- Short turn-off time
- Planar passivated chip
- Long-term stability

Applications:

- Softstart AC motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: TO-268AA (D3Pak-HV)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- High creepage distance between terminals

Disclaimer Notice

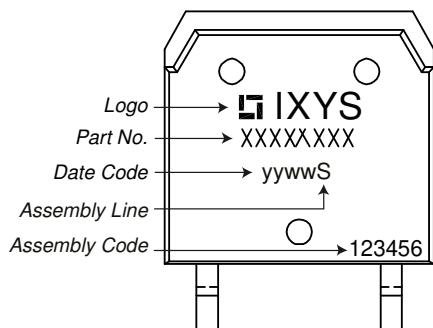
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Rectifier

Symbol	Definition	Conditions	Ratings		
			min.	typ.	max.
V_{RSM/DSM}	max. non-repetitive reverse/forward blocking voltage	T _{VJ} = 25°C			2300 V
V_{RRM/DRM}	max. repetitive reverse/forward blocking voltage	T _{VJ} = 25°C			2200 V
I_{R/D}	reverse current, drain current	V _{R/D} = 2200 V V _{R/D} = 2200 V	T _{VJ} = 25°C T _{VJ} = 125°C		20 μA 2 mA
V_T	forward voltage drop	I _T = 60 A	T _{VJ} = 25°C		2,52 V
		I _T = 120 A			3,02 V
		I _T = 60 A	T _{VJ} = 125°C		2,62 V
		I _T = 120 A			3,33 V
I_{TAV}	average forward current	T _C = 80°C	T _{VJ} = 150°C		60 A
I_{T(RMS)}	RMS forward current	180° sine			94 A
V_{T0} r_T	threshold voltage slope resistance } for power loss calculation only		T _{VJ} = 150°C		1,90 V 12,6 mΩ
R_{thJC}	thermal resistance junction to case				0,3 K/W
R_{thCH}	thermal resistance case to heatsink			0,15	K/W
P_{tot}	total power dissipation		T _C = 25°C		415 W
I_{TSM}	max. forward surge current	t = 10 ms; (50 Hz), sine	T _{VJ} = 45°C		850 A
		t = 8,3 ms; (60 Hz), sine	V _R = 0 V		920 A
		t = 10 ms; (50 Hz), sine	T _{VJ} = 150°C		725 A
		t = 8,3 ms; (60 Hz), sine	V _R = 0 V		780 A
I²t	value for fusing	t = 10 ms; (50 Hz), sine	T _{VJ} = 45°C		3,62 kA²s
		t = 8,3 ms; (60 Hz), sine	V _R = 0 V		3,52 kA²s
		t = 10 ms; (50 Hz), sine	T _{VJ} = 150°C		2,63 kA²s
		t = 8,3 ms; (60 Hz), sine	V _R = 0 V		2,53 kA²s
C_J	junction capacitance	V _R = 400V f = 1 MHz	T _{VJ} = 25°C	17	pF
P_{GM}	max. gate power dissipation	t _P = 30 μs	T _C = 150°C		10 W
		t _P = 300 μs			5 W
P_{GAV}	average gate power dissipation				0,5 W
(di/dt)_{cr}	critical rate of rise of current	T _{VJ} = 150°C; f = 50 Hz	repetitive, I _T = 180 A		150 A/μs
		t _P = 200 μs; di _G /dt = 0,3 A/μs;			
		I _G = 0,45A; V _D = 2/3 V _{DRM}	non-repet., I _T = 60 A		500 A/μs
(dv/dt)_{cr}	critical rate of rise of voltage	V _D = 2/3 V _{DRM}	T _{VJ} = 150°C		1000 V/μs
		R _{GK} = ∞; method 1 (linear voltage rise)			
V_{GT}	gate trigger voltage	V _D = 6 V	T _{VJ} = 25°C		1,4 V
			T _{VJ} = -40°C		1,6 V
I_{GT}	gate trigger current	V _D = 6 V	T _{VJ} = 25°C		± 80 mA
			T _{VJ} = -40°C		± 200 mA
V_{GD}	gate non-trigger voltage	V _D = 2/3 V _{DRM}	T _{VJ} = 150°C		0,2 V
I_{GD}	gate non-trigger current				± 5 mA
I_L	latching current	t _P = 10 μs	T _{VJ} = 25°C		450 mA
		I _G = 0,3A; di _G /dt = 0,3 A/μs			
I_H	holding current	V _D = 6 V R _{GK} = ∞	T _{VJ} = 25°C		100 mA
t_{gd}	gate controlled delay time	V _D = 1/2 V _{DRM}	T _{VJ} = 25°C		2 μs
		I _G = 0,5A; di _G /dt = 0,5 A/μs			
t_q	turn-off time	V _R = 100 V; I _T = 60A; V _D = 2/3 V _{DRM} T _{VJ} = 125 °C di/dt = 15 A/μs; dv/dt = 20 V/μs; t _P = 200 μs		150	μs

Package TO-268AA (D3Pak-HV)

Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			70	A
T_{VJ}	virtual junction temperature		-40		150	°C
T_{op}	operation temperature		-40		125	°C
T_{stg}	storage temperature		-40		150	°C
Weight				4		g
F_c	mounting force with clip		20		120	N
$d_{Spp/App}$	creepage distance on surface / striking distance through air	terminal to terminal	9,4			mm
$d_{Spb/Abp}$		terminal to backside	5,6			mm

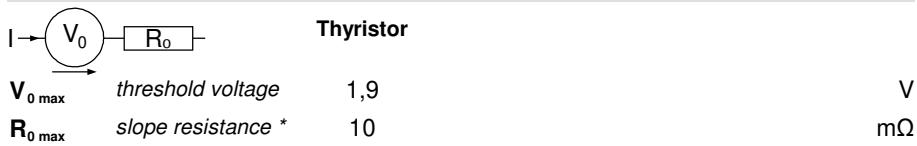
Product Marking

Part description

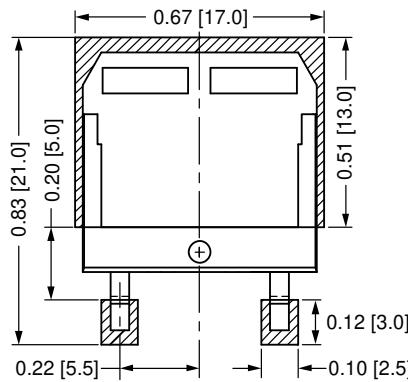
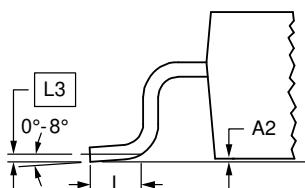
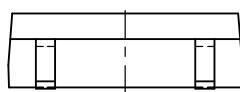
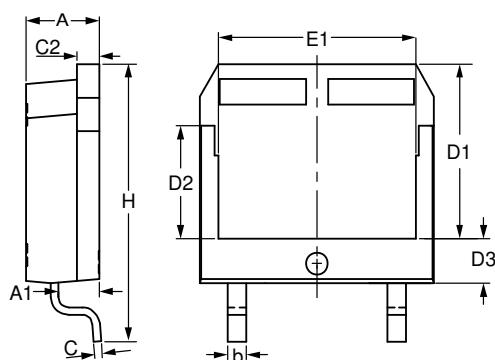
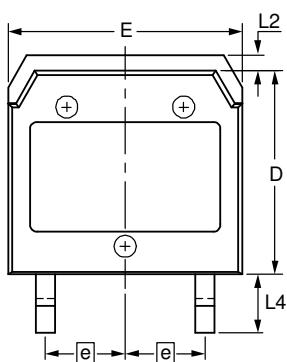
C = Thyristor (SCR)
 N = High Voltage Thyristor
 E = Semifast ($\geq 2000V$)
 60 = Current Rating [A]
 E = Single Thyristor
 2200 = Reverse Voltage [V]
 TZ = TO-268AA (D3Pak) (2HV)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CNE60E2200TZ-TUB	CNE60E2200TZ-TUB	Tube	30	524086

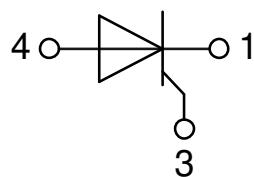
Equivalent Circuits for Simulation

* on die level

 $T_{VJ} = 150^\circ\text{C}$ 

Outlines TO-268AA (D3Pak-HV)

RECOMMENDED MINIMUM FOOT PRINT

Dim.	Millimeter		Inches	
	min	max	min	max
A	4.90	5.10	0.193	0.201
A1	2.70	2.90	0.106	0.114
A2	0.02	0.25	0.001	0.010
b	1.15	1.45	0.045	0.057
C	0.40	0.65	0.016	0.026
C2	1.45	1.60	0.057	0.063
D	13.80	14.00	0.543	0.551
D1	11.80	12.10	0.465	0.476
D2	7.50	7.80	0.295	0.307
D3	2.90	3.20	0.114	0.126
E	15.85	16.05	0.624	0.632
E1	13.30	13.60	0.524	0.535
e	5.450	BSC	0.215	BSC
H	18.70	19.10	0.736	0.752
L	1.70	2.00	0.067	0.079
L2	1.00	1.15	0.039	0.045
L3	0.250	BSC	0.010	BSC
L4	3.80	4.10	0.150	0.161



Thyristor

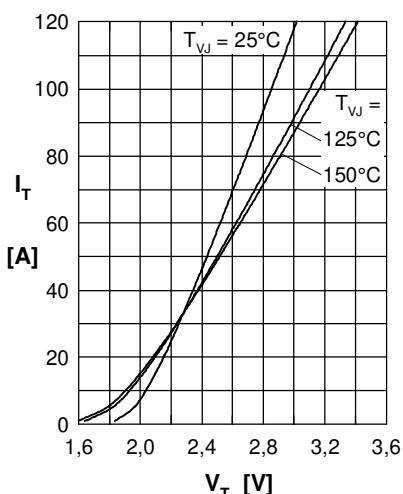


Fig. 1 Forward characteristics

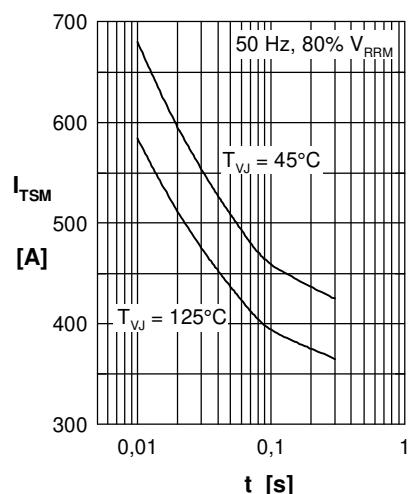
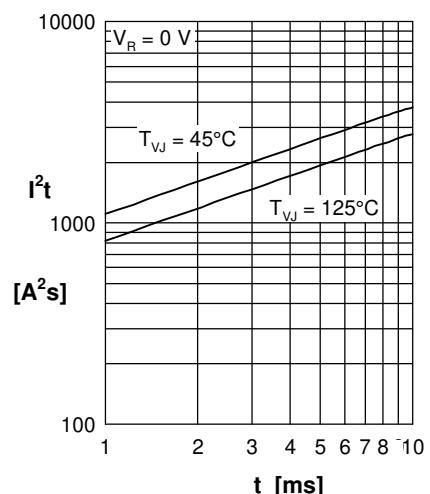
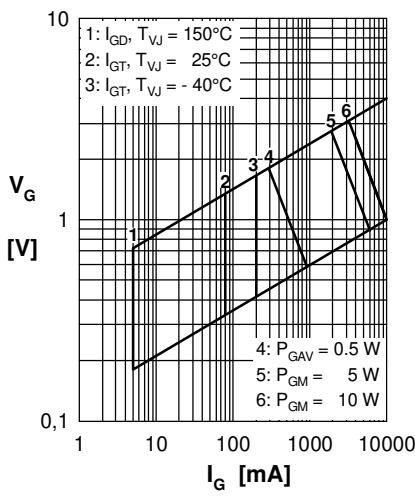
Fig. 2 Surge overload current
 $I_{TS M}$: crest value, t : durationFig. 3 I^2t versus time (1-10 s)

Fig. 4 Gate voltage & gate current

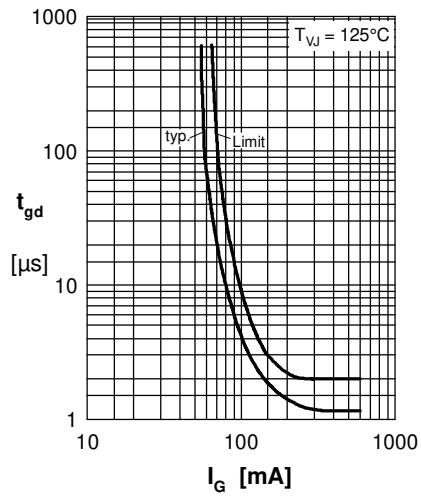
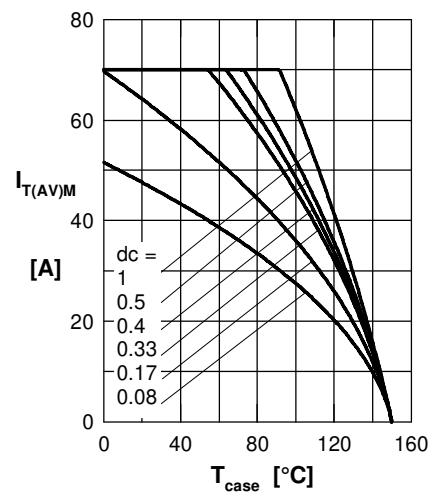
Fig. 5 Gate controlled delay time t_{gd} 

Fig. 6 Max. forward current at case temperature

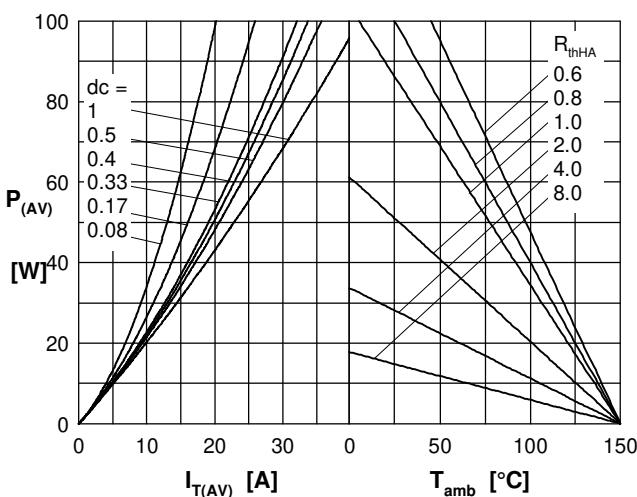
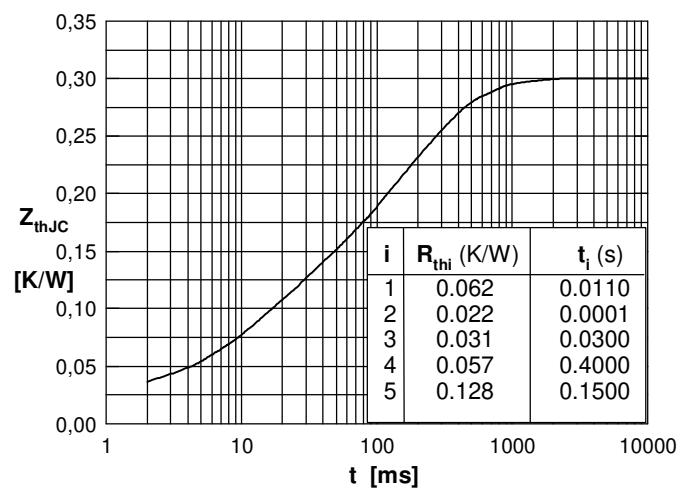
Fig. 7a Power dissipation versus direct output current
Fig. 7b and ambient temperature

Fig. 7 Transient thermal impedance junction to case